



## Advances in Applications of Metamaterials and Metasurfaces

Guest Editor:

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Deadline for manuscript  
submissions:

**closed (30 December 2023)**

### Message from the Guest Editor

Dear Colleagues,

Metamaterials and metasurfaces have garnered widespread attention in recent times due to their exceptional and highly adjustable properties. These materials are artificially designed structures constituted of bulk metallic and/or dielectric elements that exhibit remarkable electromagnetic responses, breaking the boundaries of natural materials. As a result, they exhibit vastly different electromagnetic behavior compared to traditional materials.

Both metamaterials and metasurfaces have led to remarkable advancements in several fields, including optical imaging, molecular sensing, catalysis, manufacturing, data storage, medical therapy, and energy conversion. Despite such achievements, there are still some practical challenges to overcome to achieve their full potential. You are invited to submit your work for consideration in our Special Issue.

Dr. Luigi La Spada  
*Guest Editor*





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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